



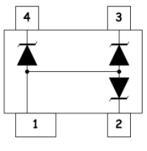
# Product data sheet

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SP0503BAHTG HF Semiconductor Compiance





SOT-143

#### Features

- Ultra low leakage: nA level
- Operating voltage: 5V
- Low clamping voltage
- Complies with following standards:
  - IEC 61000-4-2 (ESD) immunity test
    Air discharge: ±15kV
    Contact discharge: ±8kV
  - IEC61000-4-4 (EFT) 40A (5/50ns)
  - IEC61000-4-5 (Lightning) 10A
- RoHS Compliant (8/20µs)

#### **Applications**

- USB 2.0 power and data line
- Set-top box and digital TV
- Digital video interface (DVI)
- Notebook Computers
- SIM Ports
- 10/100 Ethernet

## **Mechanical Characteristics**

- Package: SOT-143
- Lead Finish: Lead Free
- UL Flammability Classification Rating 94V-0
- Quantity Per Reel:3,000pcs
- Reel Size:7inch

#### **Absolute Maximum Ratings**(Tamb=25°C unless otherwise specified)

| Parameter                       | Symbol | Value       | Unit |
|---------------------------------|--------|-------------|------|
| Peak Pulse Power (8/20µs)       | Ррр    | 150         | W    |
| ESD per IEC 61000-4-2 (Air)     |        | ±15         | Ku.  |
| ESD per IEC 61000-4-2 (Contact) | Vesd   | ±8          | Kv   |
| Operating Temperature Range     | TJ     | -55 to +125 | Ĉ    |
| Storage Temperature Range       | Тѕтј   | -55 to +150 | °C   |



#### Electrical Characteristics(TA=25°C unless otherwise specified)

| P/N         | Marking | V <sub>RWM</sub><br>(V) | Vbr<br>(V) | l⊤<br>(mA) | Vc<br>@1A | (Max) | (@A) | I <sub>R</sub><br>μΑ<br>(Max) | C<br>(Pf)<br>(Typ.) |
|-------------|---------|-------------------------|------------|------------|-----------|-------|------|-------------------------------|---------------------|
| SP0503BAHTG | 503B    | 5                       | 6          | 1          | 10        | 15    | 10   | 1                             | 30                  |

# **Characteristic Curves**

#### Fig1. 8/20µs Pulse Waveform 120 100% TEST Peak Value IPP tr Percent of Peak Pulse Current % WAVEFORM 90% 100 PARAMETERS Ipp - Peak Pulse Current - % of Ipp t<sub>r</sub>=8µs 80 t<sub>d</sub>=20µs 60 40 t<sub>d</sub>=t I<sub>PP</sub>/5 10% 20 Time (ns) -tr = 0.7~1ns 0 30ns – 0 5 10 15 20 25 30 60ns t - Time (µs)



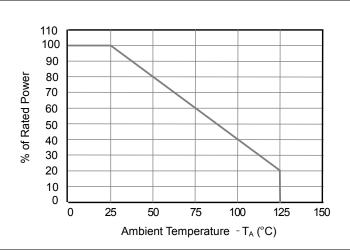


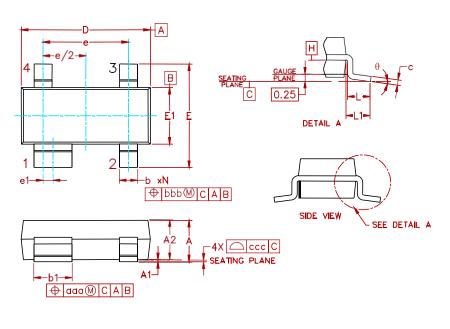
Fig2. ESD Pulse Waveform (according to IEC 61000-4-2)



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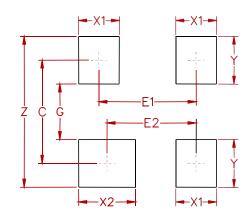
Semiconductor Compiance

#### PACKAGE MECHANICAL DATA



| Symphol | Inches            |       |       | Millimeters |      |      |  |
|---------|-------------------|-------|-------|-------------|------|------|--|
| Symbol  | Min.              | Nom.  | Max.  | Min.        | Nom. | Max. |  |
| Α       | 0.031             | -     | 0.048 | 0.80        | -    | 1.22 |  |
| A1      | 0.000             | -     | 0.008 | 0.013       | -    | 0.15 |  |
| A2      | 0.020             | 0.035 | 0.042 | 0.75        | 0.90 | 1.07 |  |
| b       | 0.011             | -     | 0.020 | 0.30        | -    | 0.51 |  |
| b1      | 0.029             | -     | 0.037 | 0.76        | -    | 0.94 |  |
| С       | 0.003             | -     | 0.008 | 0.08        | -    | 0.20 |  |
| D       | 0.110             | 0.114 | 0.120 | 2.80        | 2.90 | 3.04 |  |
| E       | 0.082             | 0.093 | 0.104 | 2.10        | 2.37 | 2.64 |  |
| E1      | 0.047             | 0.051 | 0.055 | 1.20        | 1.30 | 1.40 |  |
| е       | 0.075             |       |       | 1.92 BSC    |      |      |  |
| e1      | 0.008             |       |       | 0.20 BSC    |      |      |  |
| L       | 0.015 0.020 0.024 |       |       | 0.40        | 0.50 | 0.60 |  |
| L1      | (0.021)           |       |       | (0.54)      |      |      |  |
| N       | 4                 |       |       | 4           |      |      |  |
| θ       | 0°                | -     | 8°    | 0°          | -    | 8°   |  |
| aaa     | 0.006             |       |       | 0.15        |      |      |  |
| bbb     | 0.008             |       |       | 0.20        |      |      |  |
| ccc     | 0.004             |       |       | 0.10        |      |      |  |

## Suggested Pad Layout



#### **REEL SPECIFICATION**

| P/N         | PKG     | QTY  |
|-------------|---------|------|
| SP0503BAHTG | SOT-143 | 3000 |
|             |         |      |



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